

[**BUMP MANUFACTURING METHOD**]

Abstract of Disclosure

A method of forming bumps on the active surface of a silicon wafer. An under-ball metallic layer is formed over the active surface of the wafer. A plurality of first solder blocks is attached to the upper surface of the under-ball metallic layer. Each first solder block has an upper surface and a lower surface. The lower surface of each first solder block bonds with the under-ball metallic layer. The upper surfaces of the first solder blocks are planarized. A second solder block is attached to the upper surface of each first solder block and then a reflux operation is carried out.

Figures

Figure 1: A vertical list of text elements, possibly a table of contents or a list of items, arranged in a single column. The text is small and difficult to read, but appears to be organized in a structured manner.